



PCN# : P57MAA
Issue Date : Aug. 19, 2015

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples.

Implementation of change:

Expected First Shipment Date for Changed Product : Nov. 17, 2015

Expected First Date Code of Changed Product :1545

Description of Change (From) :

Front-end Wafer Fabrication site Fairchild Salt Lake Utah, 6-inch wafers

Back-end Assembly/Test site Fairchild Penang Malaysia

BOM Information for Assembly Site

BOM Information	Fairchild Penang	
Package	Molded leadless package (MLP) / Ultrathin MLP (UMLP)	Pre-mold Micropak/MicroMLP (uMLP)
Leadframe	ASM/HaeSung DS / Sumitomo PPF (pre-plated leadframe)	
Die attach	Henkel QMIS19 / Hitachi EN-4620K / Henkel 8008-HT / Lintec LE5003	Lintec LE5003
Wire bonding	0.8, 1, 1.3, 1.5, 2 mil Au wire / 1.0, 1.5, 2 mil PdCu / Cu	0.8 mils Au wire
Mold Compound	Hitachi CEL9220HF13FC1 (Green)	Cookson CK203P (Premold), CK203M (Final Mold) (Green)
Terminal Finish	NiPdAuAg / NiPdAu	

Description of Change (To) :

Front-end Wafer Fabrication site Tower Jazz Israel Foundry, 8-inch wafers and Fairchild Mt. Top, PA 8-inch wafers
Back-end Assembly/Test site Subcon Hana, UTAC, and GEM

Product ID	New Wafer Fab Locations	New Assembly Sites
FAN2106EMPX	Tower Jazz Israel 8-inch	Hana & UTAC, Thailand
FAN21SV06EMPX	Tower Jazz Israel 8-inch	HANA, Thailand
FAN21SV06MPX	Tower Jazz Israel 8-inch	Hana & UTAC, Thailand
FAN21SV06MPX_SN00220	Tower Jazz Israel 8-inch	HANA, Thailand
FDMS9620S_F106	Tower Jazz Israel 8-inch	HANA, Thailand
FDS6982AS_F095	Tower Jazz Israel 8-inch	GEM, Philippines

BOM Information for Assembly Sites

BOM Information	Hana AYT		UTAC		GEM
Package	Molded leadless package (MLP) / Ultrathin MLP (UMLP)	Micropak/MicroMLP (uMLP)	Molded leadless package (MLP) / Ultrathin MLP (UMLP)	Micropak/MicroMLP (uMLP)	SOIC 8L
Leadframe	HaeSung DS RT UPG1 PPF	ASM ME2 PPF / Kinsus Bt CCL-HL832 Substrate	HaeSung DS RT UPG1 PPF	HaeSung DS RT UPG1 PPF / Sumitomo selective PPF	Bare Cu
Die attach	Henkel 8600 / CDF215	Henkel 8006NS, Lintec LE5003	Henkel 8600 / CDF550	Henkel 8006NS / Henkel 8600	ABP8062T / CT285
Wire bonding	0.8, 1, 1.3, 1.5, 2 mil Au wire / 1.0, 1.5, 2 mil PdCu / Cu	0.8 mils Au wire	0.8, 1, 1.3, 1.5, 2 mil Au wire / 1.0, 1.5, 2 mil PdCuAg	0.8 mils Au wire	Cu/Au wire
Mold Compound	Hitachi CEL9220HF13H (Green)		Sumitomo G700LTD / G770HCD (Green)	Sumitomo G700LTD / G770HCD (Green) Panasonic CV8715BT (Green)	G600FL
Terminal Finish	NiPdAuAg	NiPdAu / NiAu	NiPdAuAg	NiPdAuAg / NiPdAu	Sn

Reason for Change:

Improve supply flexibility.

Better quality and yields through equipment and facility upgrades.

- Increased automation in handling and inspection in assembly.

Fairchild partners with foundries and assembly subcontractors.

- Best manufacturing practices, access to many customers methods and practices.

- Advanced technology for fast ramp of future new products and technologies.

Affected Product(s): Please refer to the list of affected products in the addendum attached in the PCN email you received. This list is based on an analysis of your company's procurement history.

Qualification Plan	Device	Package	Process	No. of Lots
Q20140144A	FDS8958A_F085	NMSOD 8L	PT3 N	3

Test Description:	Condition:	Standard:	Duration:	Results:
Preconditioning, MSL 1	260°C, 3 cycles	JESD22-A113	NA	Sept 15
Highly Accelerated Stress Test	130°C, 85%RH, Vr = 24V	JESD22-A110	96 hrs	Sept 15
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	Sept 15
High Temperature Reverse Bias	150C, 30V	JESD22-A108	1000 hrs	Sept 15
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	Sept 15
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	Sept 15
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	Sept 15
Unbiased Highly Accelerated Stress Test	85%RH, 130C	JESD22-A118	96 hrs	Sept 15
Resistance to Solder Heat	260°C	JESD22-B106	10 sec	Sept 15
Destructive Physical Analysis (after TMCL)	NA	AEC-Q101-004 Section 4	NA	Sept 15

Qualification Plan	Device	Package	Process	No. of Lots
Q20140198	FDMS9600S	MLP56 Dual Dap	TB3 N	3

Test Description:	Condition:	Standard:	Duration:	Results:
MSL1 Precondition	260°C, 3 cycles	JESD22-A113	NA	Apr 28
Highly Accelerated Stress Test	130°C, 85%RH, Vr = 24V	JESD22-A110	96 hrs	May 8
High Temperature Gate Bias	150°C, Vgs = 20V	JESD22-A108	1000 hrs	June 3
High Temperature Reverse Bias	125°C, Vr = 24V	JESD22-A108	1000 hrs	June 3
High Temperature Storage Life	150°C	JESD22-A103	1000 hrs	June 19
Power Cycle	Delta 125CC, 2 Min cycle	MIL-STD-750-1036	7500 cyc	June 3
Temperature Cycle	-65°C, 150°C	JESD22-A104	500 cyc	May 22
Resistance to Solder Heat	260°C	JESD22-B106	10 sec	Apr 20

Qualification Plan	Device	Package	Process	No. of Lots
Q20140194	FDS6910	NMSOD 8L	Salt Lake PT3 N	1

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Lead Integrity	30 degree, 3Oz.	JESD22-B105	3 cyc	0/10
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140194	FDS2734	NMSON 8L	Mountain Top UFET TRENCH	1

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Reverse Bias	150C, 200V	JESD22-A108	1000 hrs	0/77
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140194	FDS6699S	NMSON 8L	Salt Lake PT3 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	125C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Lead Integrity	30 degree, 3Oz.	JESD22-B105	3 cyc	0/10
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140194	FDS6982AS	NMSOD 8L	Mountain Top/Salt Lake PT3 N/PT3 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	125C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Lead Integrity	30 degree, 3Oz.	JESD22-B105	3 cyc	0/10
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FAN2106MPX	MLDEMC25	Maine CBIH30VD Salt Lake PT3 N/PT3 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FDMS2734	MLDAMC08	Mountain Top UFET Trench	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 42V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, 200V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FDMS7620S	MLDAMCX8	TSMC Taiwan PT7 N/PT7 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FIN210ACMLX	MLDFL032	Maine FS35C3LMD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FXLA108BQX	MLDFX020	Maine 35CTINYBD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 3.6V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, 3.6V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FDML7610S	MLDEZCX8	Salt Lake PT7 N/PT7 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	125C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FDMA7628	MLDEBCC6	Salt Lake PT4 N	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 16V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 8V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, 16V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FDMC6683	MLDEUC08	Salt Lake ST3 P	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, -16V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, -8V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, -16V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140208A	FDMC86261P	MLDEUC08	Salt Lake MV5 P	1

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Reverse Bias	150C, -120V	JESD22-A108	1000 hrs	0/77
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140001	FDMC6676BZ	MLDEUC08	ST3 PZ	3

Test Description:	Condition	Standard	Duration	Result/FA
High Temperature Gate Bias	150C, Vgs=20V	JESD22-A108	1000hrs	0/237
High Temperature Reverse Bias	150C, Vr=80V	JESD22-A108	1000hrs	0/237
High Temperature Storage Life	175C	JESD22-A103	500hrs	0/237
Highly Accelerated Stress Test	130C, 85%RH, Vr=42V	JESD22-A110	96hrs	0/237
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/66
Power Cycle	Delta 100C, 2 Min cycle	Mil Std 750-1036	10000cyc	0/237
Temperature Cycle	-65C,150C	JESD22-A104	500cyc	0/237

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	NC7SV08FHX	PFH88006	Maine 35CTNYBD	3

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/231
Highly Accelerated Stress Test	85%RH, 130C, 3.6V	JESD22-A110	96 hrs	0/231
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
Static Operating Life	150C, 3.3V	JESD22-A108	1000 hrs	0/231
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/231
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/30
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/33
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/33
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/66

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	FSA642UMX	PFGOX024	Maine FS35C32BD	3

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/231
Highly Accelerated Stress Test	85%RH, 130C, 4.6V	JESD22-A110	96 hrs	0/231
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
Static Operating Life	150C, 4.6V	JESD22-A108	1000 hrs	0/231
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/231
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/30
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/33
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/33
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/66

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	FDMA6023PZT	MFEJJX06	Bucheon ST3 BGBM	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, -16V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, -8V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, -16V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	FPF1018	MFEJJA06	Maine FS35C32BD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 1.8V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, 1.8V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	FSA9280AUMX	MFFT5020	Maine 35D540SBD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 3.3V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, Vcc=5.5V, VLD=3.3V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	FSA1211UMX	MFGY5028	Maine FS35C32BD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	FXLA0104QFX	PFGGJ012	Maine FS35CD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Unbias Highly Accelerated Stress Test	85%RH, 130C	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	FSA8038UMSX_F106	PFGDHA10	Maine 35D540BD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 4.5V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, 3.0V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	NC7SZ00L6X	MLLF4006	Maine C5LBPOAD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 5.0V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, 5.0V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140207	FAN256L8X_F106	MLLF5008	Maine FS50BPOAD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 5.0V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, 5.0V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140197	NC7SV08FHX	PFH88006	Maine 35CTNYBD	2

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/154
Highly Accelerated Stress Test	85%RH, 130C, 3.6V	JESD22-A110	96 hrs	0/154
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/154
Static Operating Life	150C, 3.3V	JESD22-A108	1000 hrs	0/154
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/154
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/20
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/22
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/22
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/44

Qualification Plan	Device	Package	Process	No. of Lots
Q20140197	FSA642UMX	PFGOX024	Maine FS35C32BD	3

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/231
Highly Accelerated Stress Test	85%RH, 130C, 4.6V	JESD22-A110	96 hrs	0/231
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/231
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/30
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/33
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/33
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/66

Qualification Plan	Device	Package	Process	No. of Lots
Q20140197	FDMA6023PZT	MFEJJX06	Bucheon ST3 BGBM	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, -16V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, -8V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, -16V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140197	FPF1018	MFEJJA06	Maine FS35C32BD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 1.8V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, 1.8V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140197	FSA9280AUMX	MFFT5020	Maine 35D540SBD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 3.3V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, Vcc=5.5V, VLD=3.3V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140197	FSA1211UMX	MFGY5028	Maine FS35C32BD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FDMS2734	MLDAMC08	Mountain Top UFET Trench	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 42V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, 200V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FDMS7620S	MLDAMCX8	Salt Lake PT7 N/PT7 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	125C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FIN210ACMLX	MLDFL032	Maine FS35C3LMD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Unbias Highly Accelerated Stress Test	85%RH, 130C	JESD22-A110	96 hrs	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FXLA108BQX	MLDFX020	Maine 35CTINYBD	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 3.6V	JESD22-A110	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Static Operating Life	150C, 3.6V	JESD22-A108	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FDML7610S	MLDEZCX8	Salt Lake PT7 N/PT7 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
Highly Accelerated Stress Test	85%RH, 130C, 24V	JESD22-A110	96 hrs	0/77
High Temperature Gate Bias	150C, 20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	125C, 24V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20140192	FDMC86261P	MLDEUC08	Salt Lake MV5 P	1

Test Description:	Condition:	Standard:	Duration:	Results:
High Temperature Reverse Bias	150C, -120V	JESD22-A108	1000 hrs	0/77
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
QP13031025 (CP20140002)	FDMS86201	PQFN08A	MV5N/MV5NZ	1

Test Description:	Condition	Standard	Duration	Result
High Temperature Gate Bias	150C, Vgs=20V	JESD22-A108	1000 hrs	0/77
High Temperature Reverse Bias	150C, Vr=96V	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Highly Accelerated Stress Test	130C, 85%RH, Vr=42V	JESD22-A110	96 hrs	0/77
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/77
Temperature Cycle	-65C,150C	JESD22-A104	500 cyc	0/77

Qualification Plan	Device	Package	Process	No. of Lots
QP13031025 (CP20140002)	FDMS86200DC	PQFN08D	MV5N/MV5NZ	3

Test Description:	Condition	Standard	Duration	Result
High Temperature Gate Bias	150C, Vgs=20V	JESD22-A108	1000 hrs	0/231
High Temperature Reverse Bias	150C, Vr=120V	JESD22-A108	1000 hrs	0/231
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
Highly Accelerated Stress Test	130C, 85%RH, Vr=42V	JESD22-A110	96 hrs	0/231
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/231
Temperature Cycle	-65C,150C	JESD22-A104	500 cyc	0/231

Qualification Plan	Device	Package	Process	No. of Lots
QP12120985G (CP20130016)	FDMS0300S	PQFN	N-Channel Power Trench 8 SyncFET	3

Test Description:	Condition	Standard	Duration	Result
High Temperature Gate Bias	150C, Vgs=20V	JESD22-A108	1000 hrs	0/231
High Temperature Reverse Bias	150C, Vr=80V	JESD22-A108	1000 hrs	0/231
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
Highly Accelerated Stress Test	130C, 85%RH, Vr=42V	JESD22-A110	96 hrs	0/231
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/231
Temperature Cycle	-65C,150C	JESD22-A104	500 cyc	0/231

Qualification Plan	Device	Package	Process	No. of Lots
QP13181047 (CP20130033)	FDMS7656AS	PQFN	N-Channel Power Trench 7 SyncFET	3

Test Description:	Condition	Standard	Duration	Result
High Temperature Gate Bias	150C, Vgs=20V	JESD22-A108	1000 hrs	0/231
High Temperature Reverse Bias	150C, Vr=80V	JESD22-A108	1000 hrs	0/231
Highly Accelerated Stress Test	130C, 85%RH, Vr=42V	JESD22-A110	96 hrs	0/231

Qualification Plan	Device	Package	Process	No. of Lots
QP13011024A (CP20130039)	FDMS7650DC	PQFN_56CLP	PT7 N S	3

Test Description:	Condition	Standard	Duration	Result
High Temperature Gate Bias	150C, Vgs=20V	JESD22-A108	1000 hrs	0/231
High Temperature Reverse Bias	150C, Vr=80V	JESD22-A108	1000 hrs	0/231
High Temperature Storage Life	175C	JESD22-A103	500 hrs	0/231
Highly Accelerated Stress Test	130C, 85%RH, Vr=42V	JESD22-A110	96 hrs	0/231
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/231
Temperature Cycle	-65C,150C	JESD22-A104	500 cyc	0/231

Qualification Plan	Device	Package	Process	No. of Lots
QP13011024A (CP20130039)	FDMC8010	PQFN_33PC	PT8 N S	3

Test Description:	Condition	Standard	Duration	Result
High Temperature Gate Bias	150C, Vgs=20V	JESD22-A108	1000 hrs	0/231
High Temperature Reverse Bias	150C, Vr=80V	JESD22-A108	1000 hrs	0/231
High Temperature Storage Life	175C	JESD22-A103	500 hrs	0/231
Highly Accelerated Stress Test	130C, 85%RH, Vr=42V	JESD22-A110	96 hrs	0/231
Power Cycle	Delta 100C, 2 Min cycle	MIL-STD-750-1036	10000 cyc	0/231
Temperature Cycle	-65C,150C	JESD22-A104	500 cyc	0/231

Qualification Plan	Device	Package	Process	No. of Lots
Q20150051	FAN2106MPX	MLDEMC25	Maine CBIH30VD Salt Lake PT3 N/PT3 N S	1

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/77
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/10
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/11
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/11
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/22

Qualification Plan	Device	Package	Process	No. of Lots
Q20150051	FDMF6704	MLDFNYAR	Jazz US JAZZBC05D Salt Lake RP5 N/RP5 N S	2

Test Description:	Condition:	Standard:	Duration:	Results:
Auto Clave	100%RH, 121C	JESD22-A102	96 hrs	0/154
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/154
Temperature Cycle	-65C, 150C	JESD22-A104	500 cyc	0/154
Resistance to Solder Heat	260°C	JESD22-B106	3X @ 10s	0/20
Solderability, Condition A	215°C, 5 sec	JESD22-B102	8 hrs	0/22
Solderability, Condition B	245°C, 5 sec	JESD22-B102	8 hrs	0/22
MSLNL1A	PeakTemp(260°C), Cycles 3X	J-STD_020		0/44